

# **Supersonic Impact of Metallic Microparticles**

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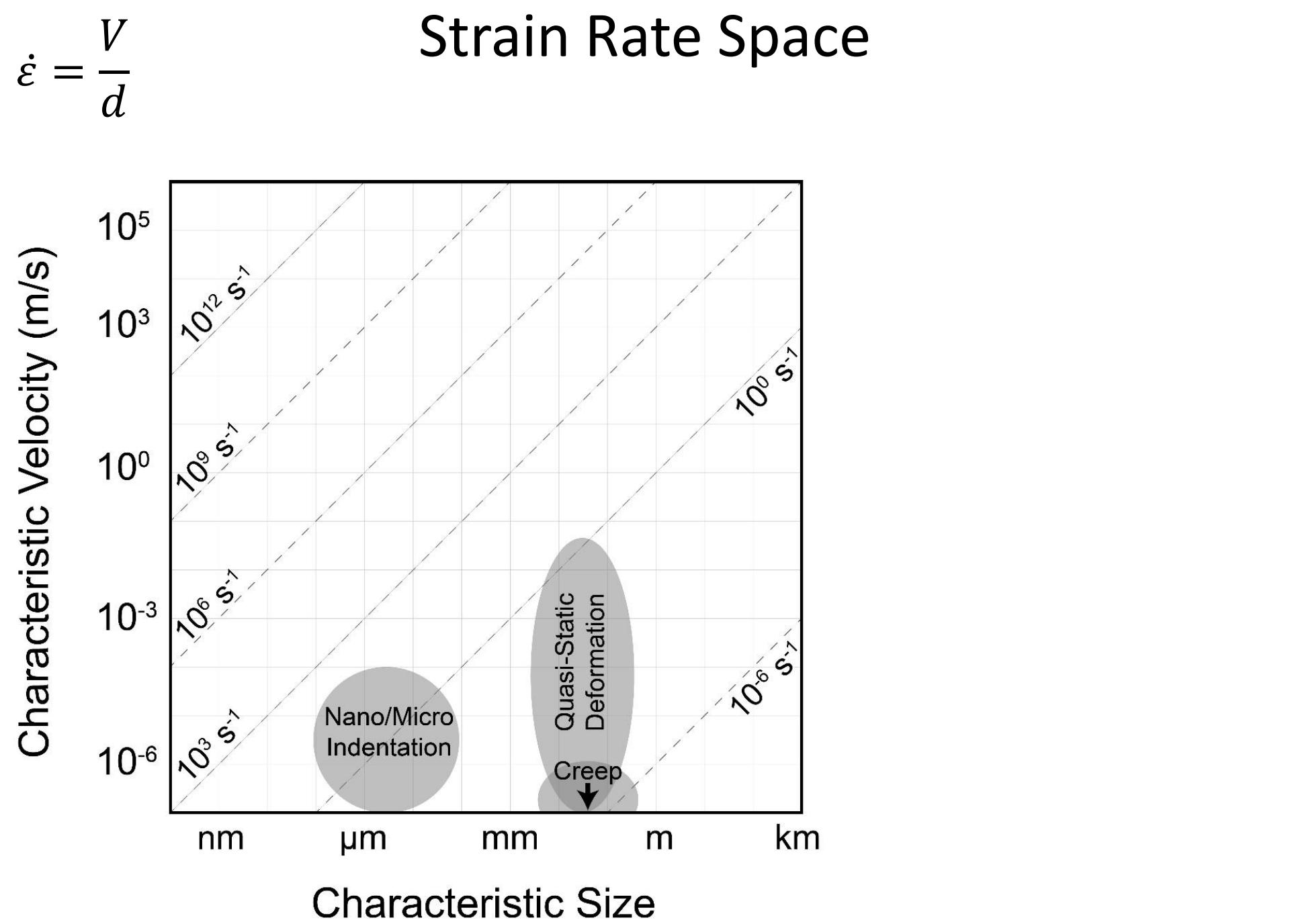
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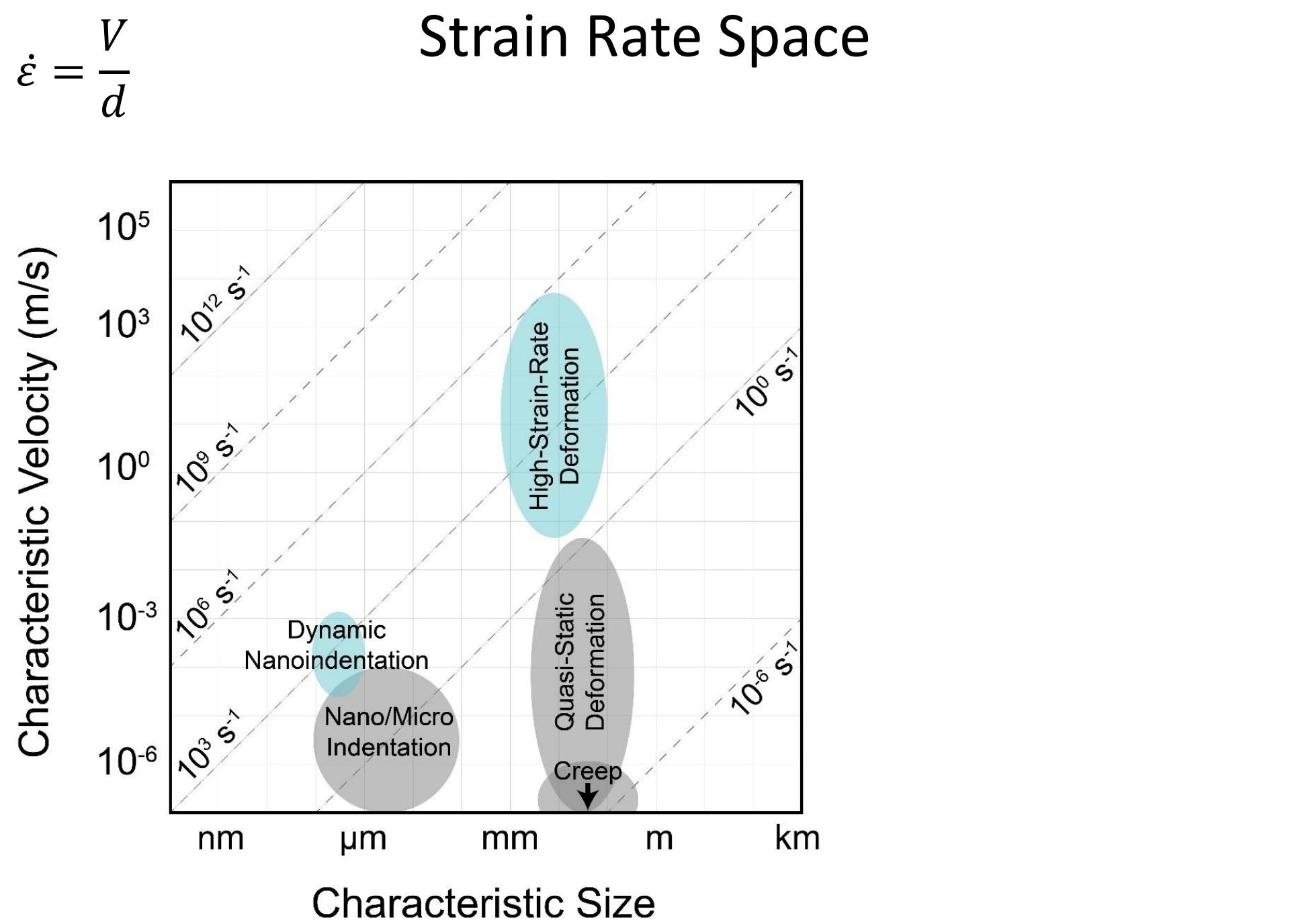
<sup>2</sup>Institute for Soldier Nanotechnologies, MIT, Cambridge, Massachusetts 02139, USA

<sup>3</sup>Department of Chemistry, MIT, Cambridge, Massachusetts 02139, USA

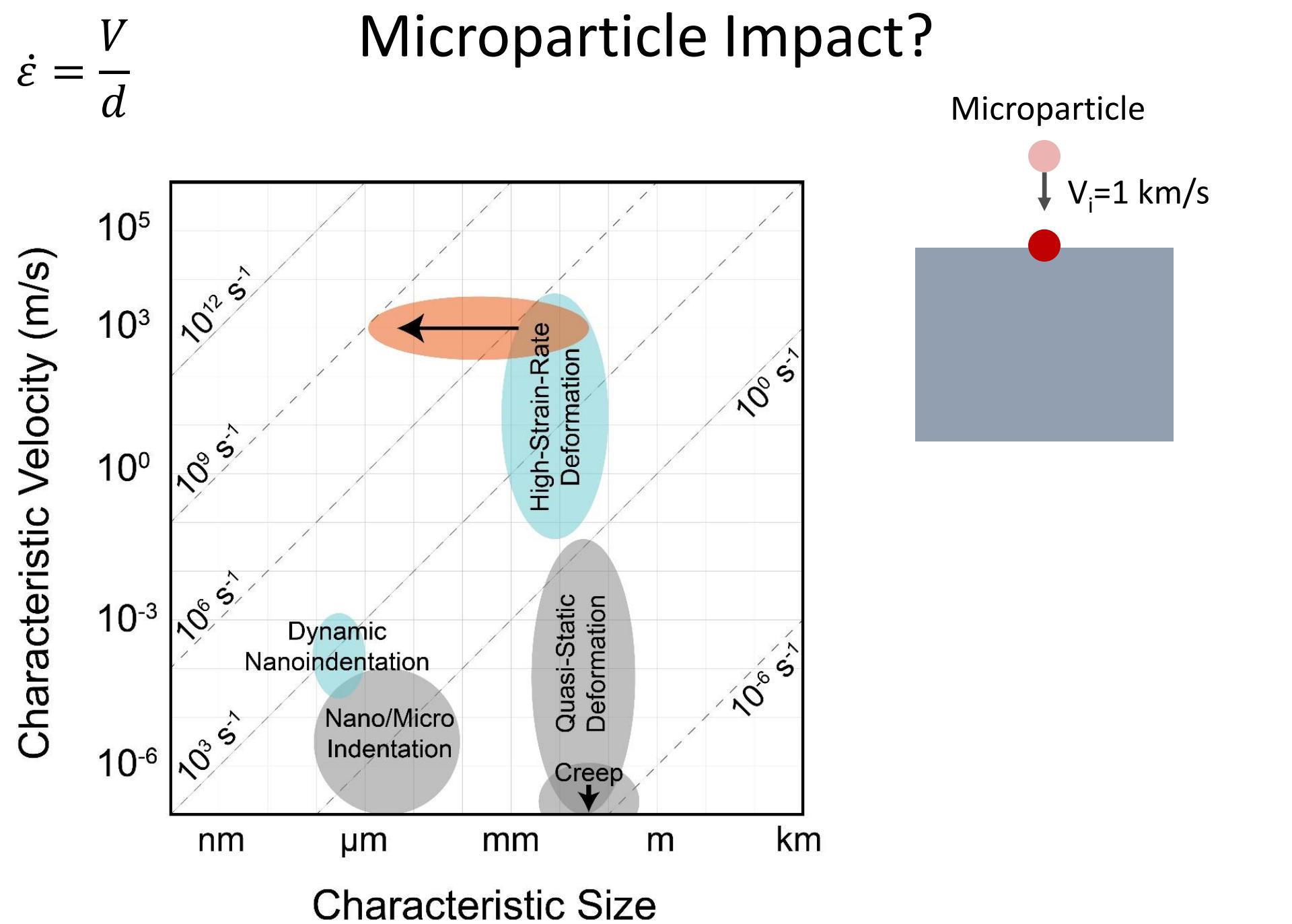
ICHSF, May 2018

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# Microparticle Impact?



# Microparticle Impact?

I. Smaller Scales, i.e., Higher Rates

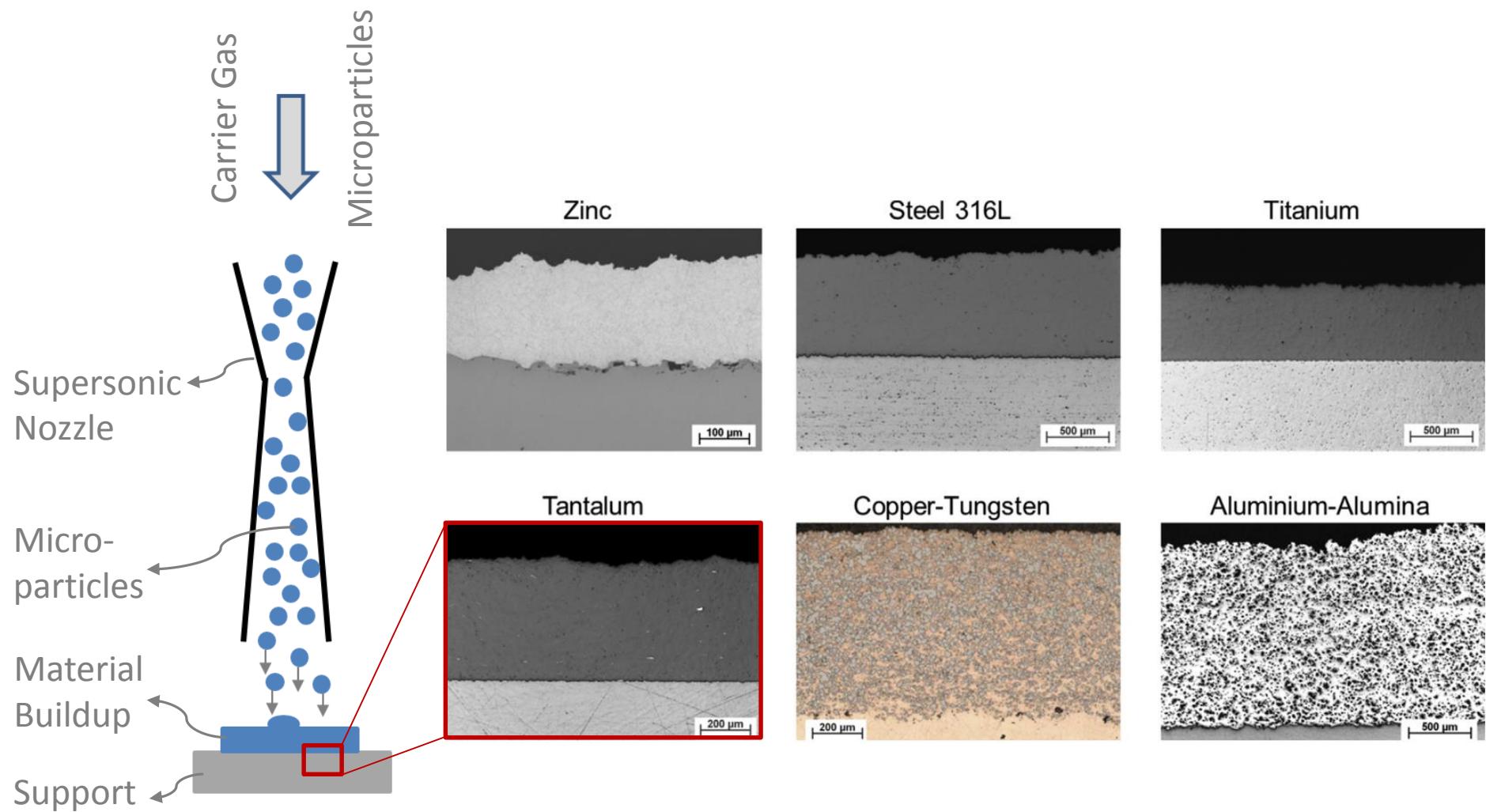
# Microparticle Impact?

- I. Smaller Scales, i.e., Higher Rates
- II. Impact for Manufacturing



GE Research, 2013

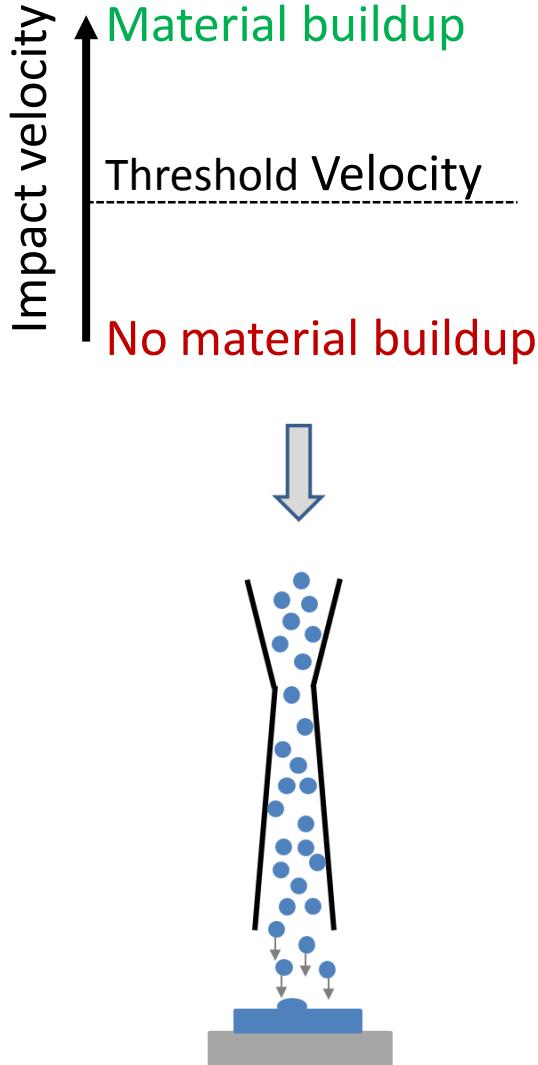
# Cold Spray



# Cold Spray



# Call for *in-situ* studies



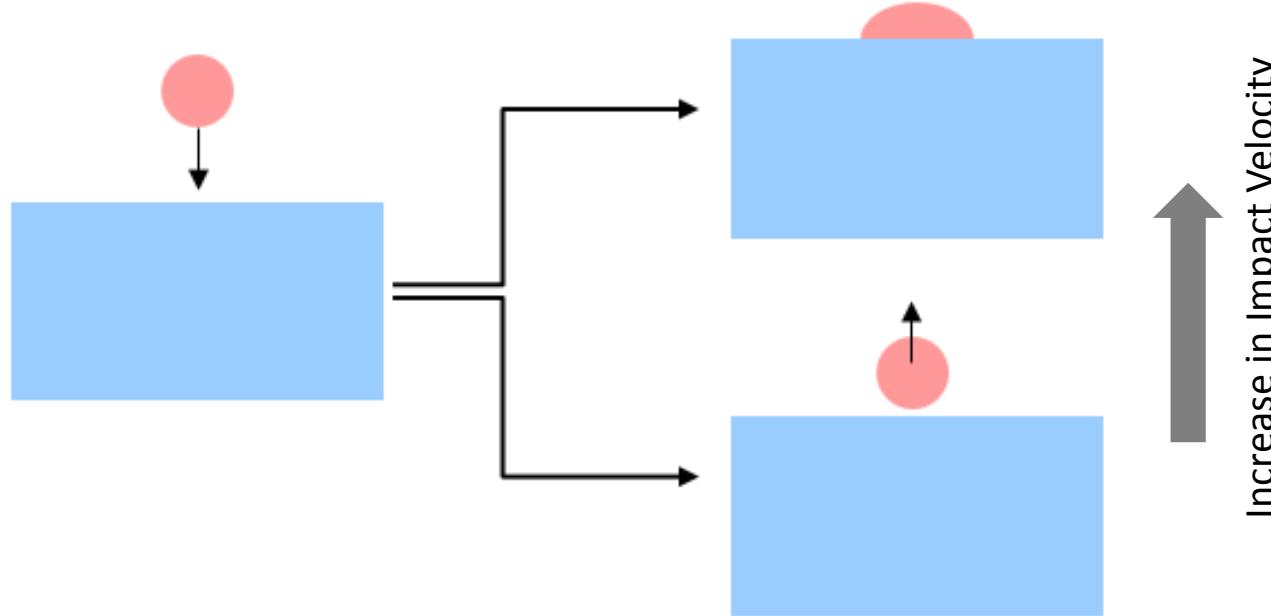
**Challenge 1.**  
**No direct measurement of  $V_{cr}$**

Only in-direct estimations based on deposition efficiency and fluid dynamics

**Challenge 2.**  
**No consensus on bonding mechanisms**

Adiabatic shear localization  
Mechanical Interlocking  
Localized melting  
Diffusion  
...

# Unit Process: Single Particle Impact



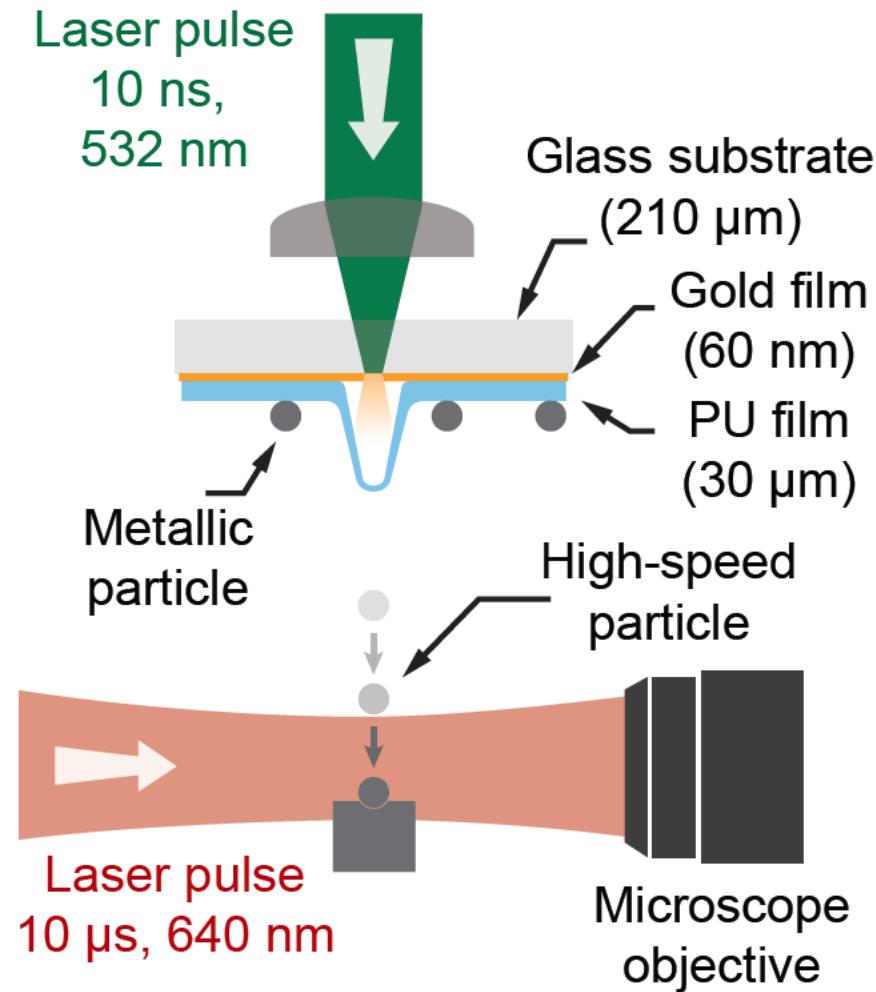
Particle size: 5-50  $\mu\text{m}$

Impact Velocity: 400-1000 m/s

Characteristic time: ~100 ns

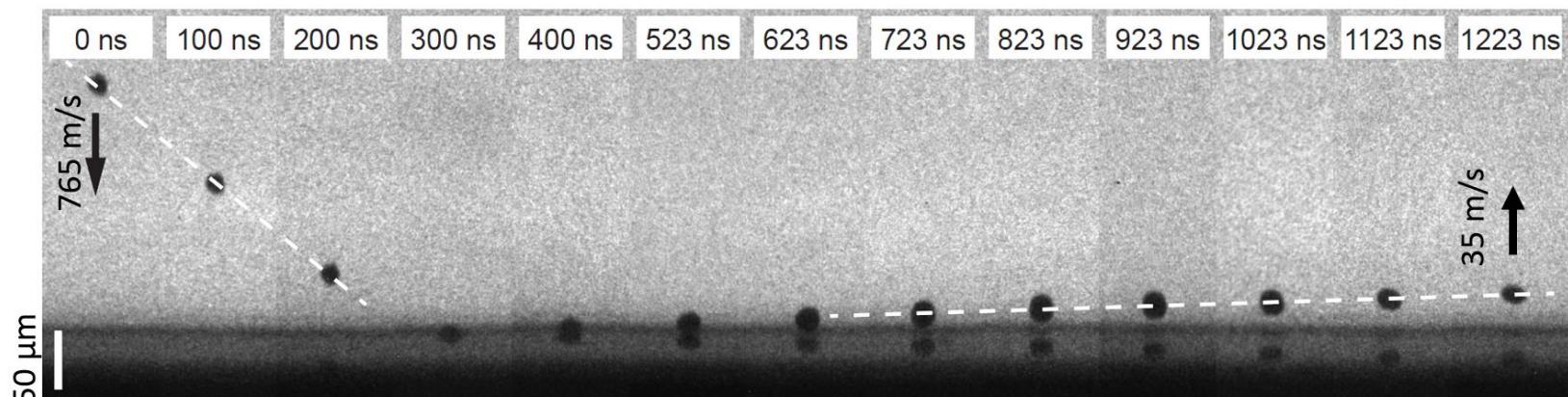
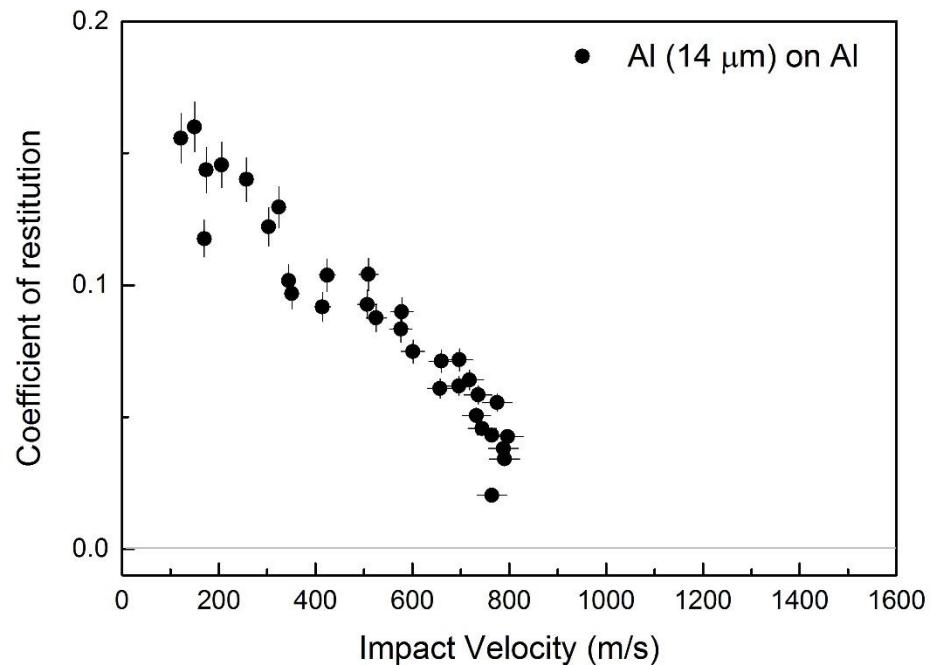
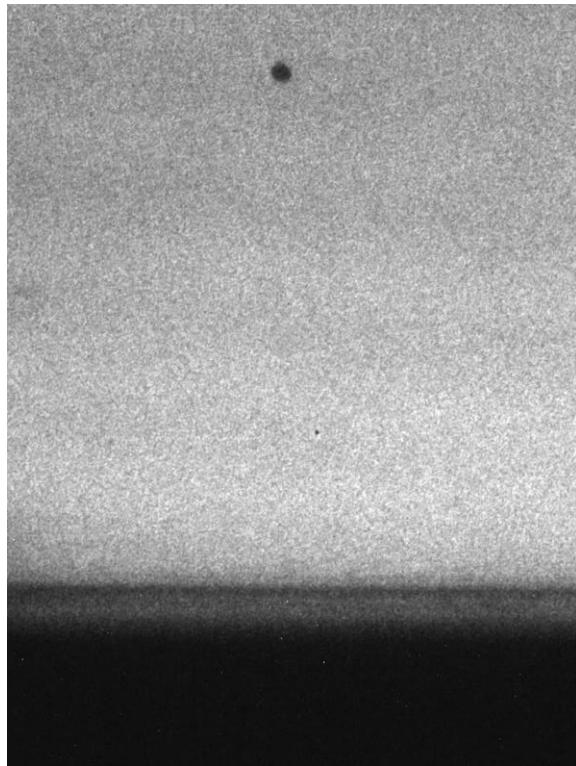
**100 million fps**

# *In-situ* studies of single microparticle impact

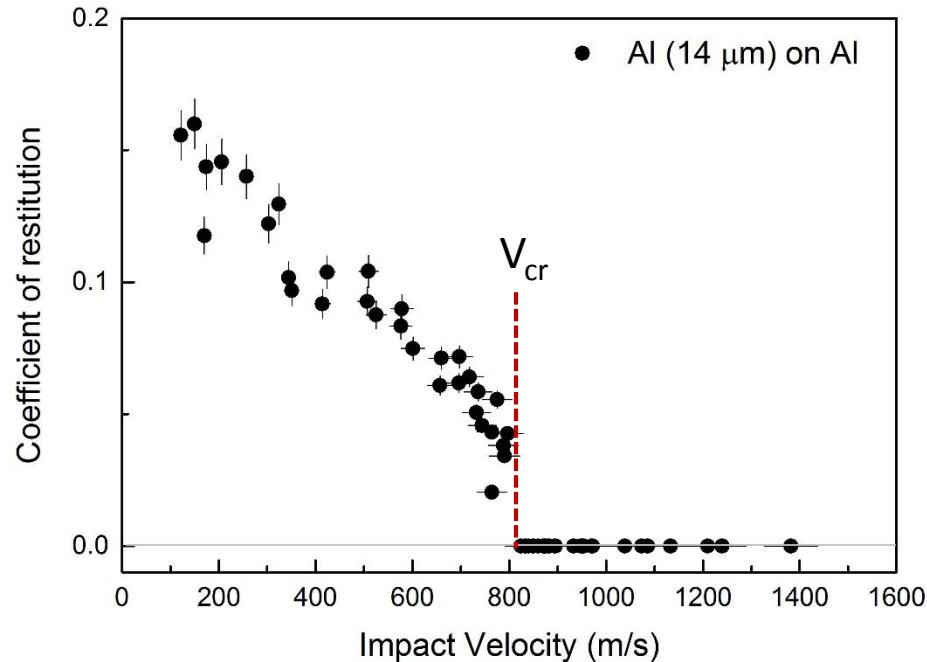
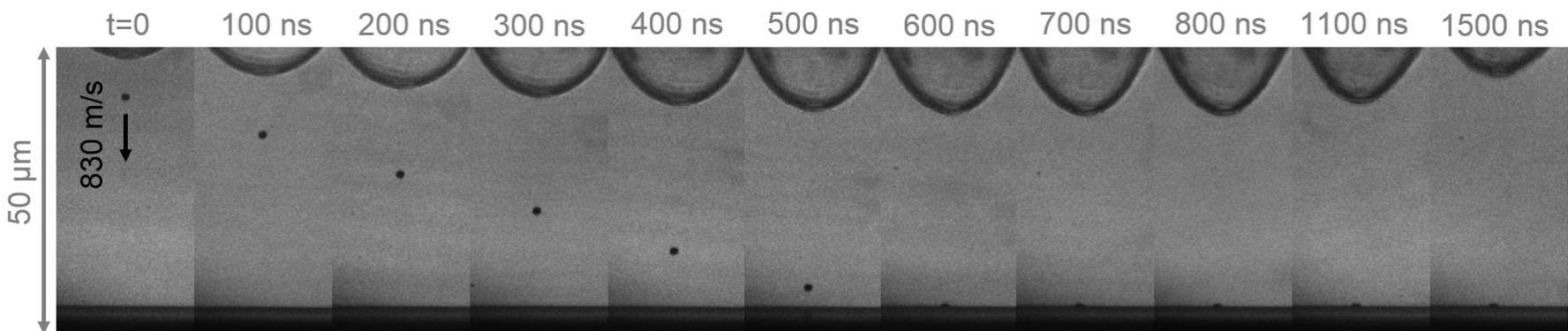
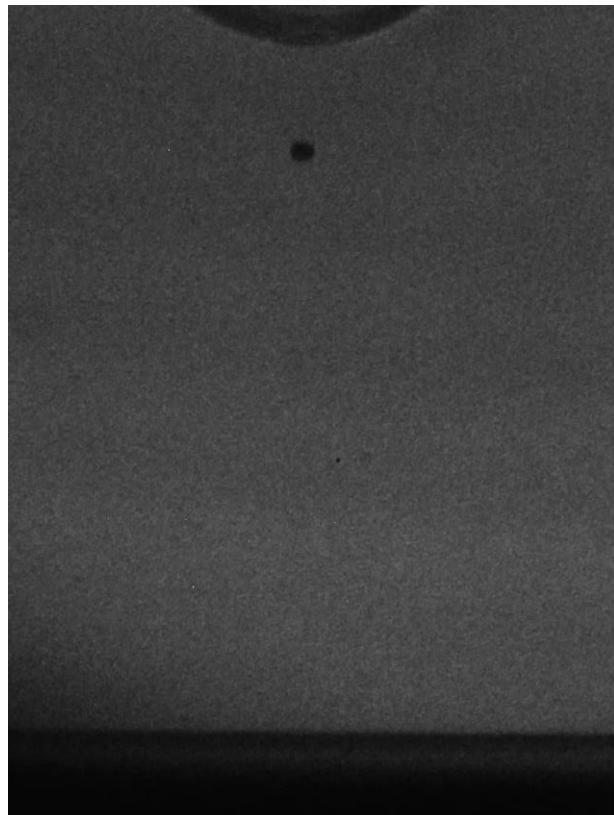


Al on Al

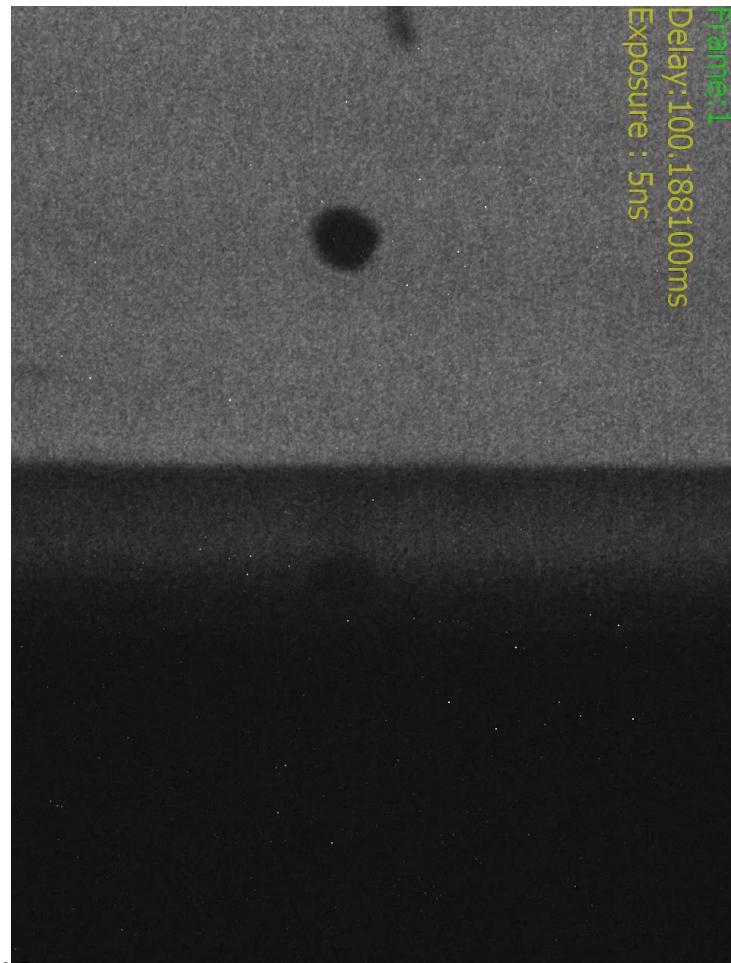
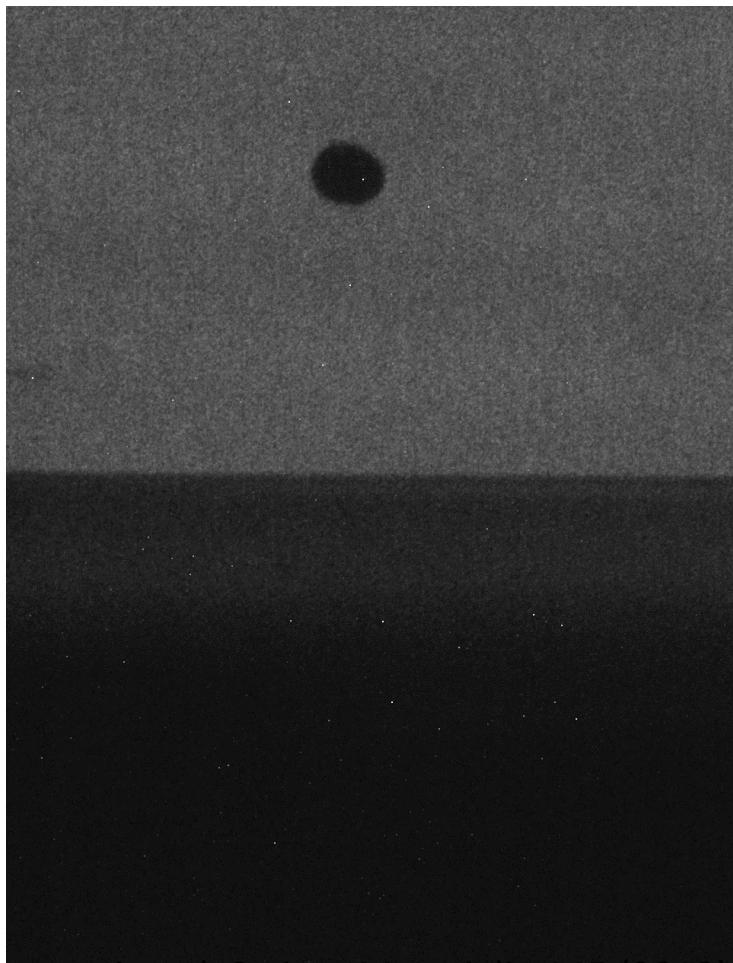
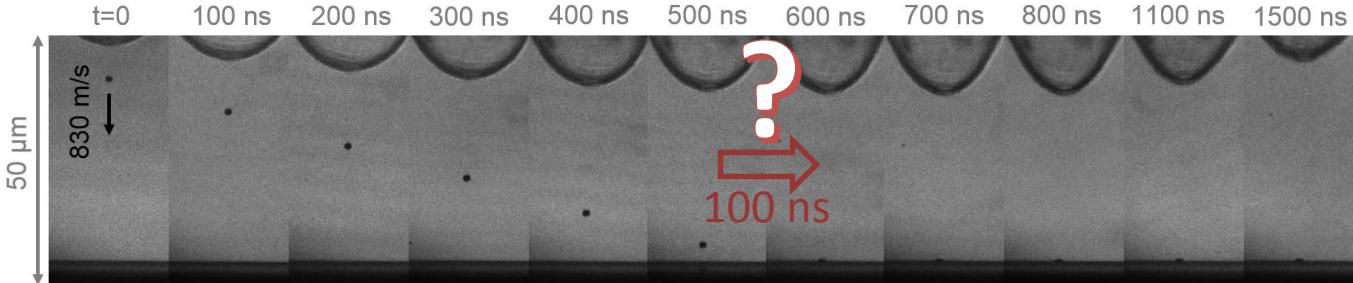
# Rebound



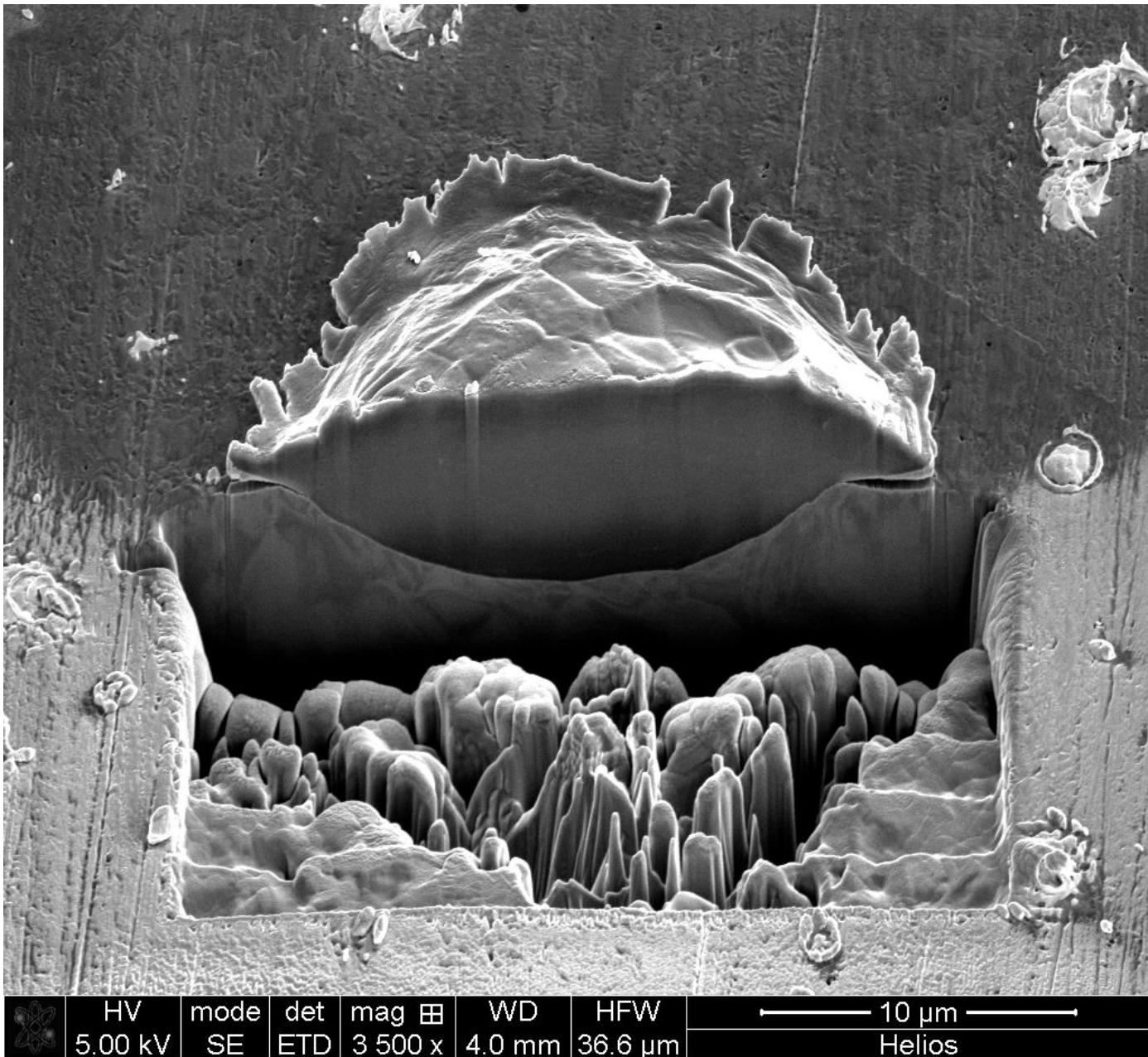
# Adhesion



# The Moment of Bonding



# Post-mortem



HV  
5.00 kV

mode  
SE

det  
ETD

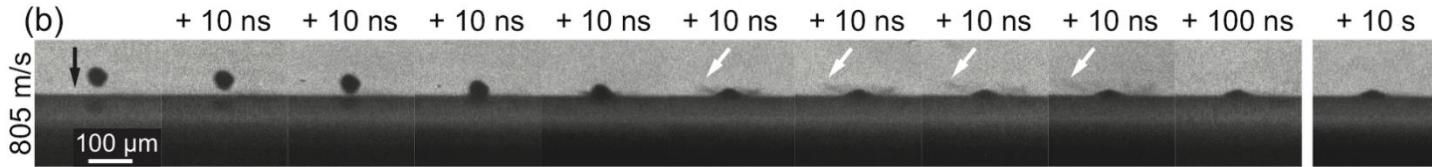
mag  
3 500 x

WD  
4.0 mm

HFW  
36.6  $\mu$ m

— 10  $\mu$ m —  
Helios

# Ejecta; Base Metal or Oxide?

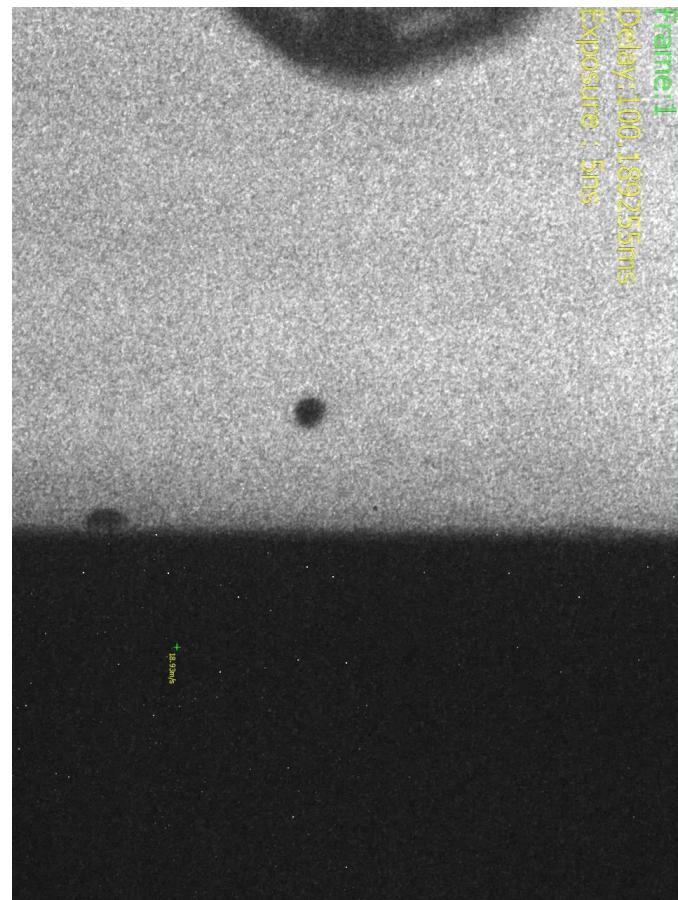


## Bonding Moment for Gold

115 m/s



310 m/s



The origin of jetting?



Adiabatic Shear Instability

Jetting leads to Bonding.



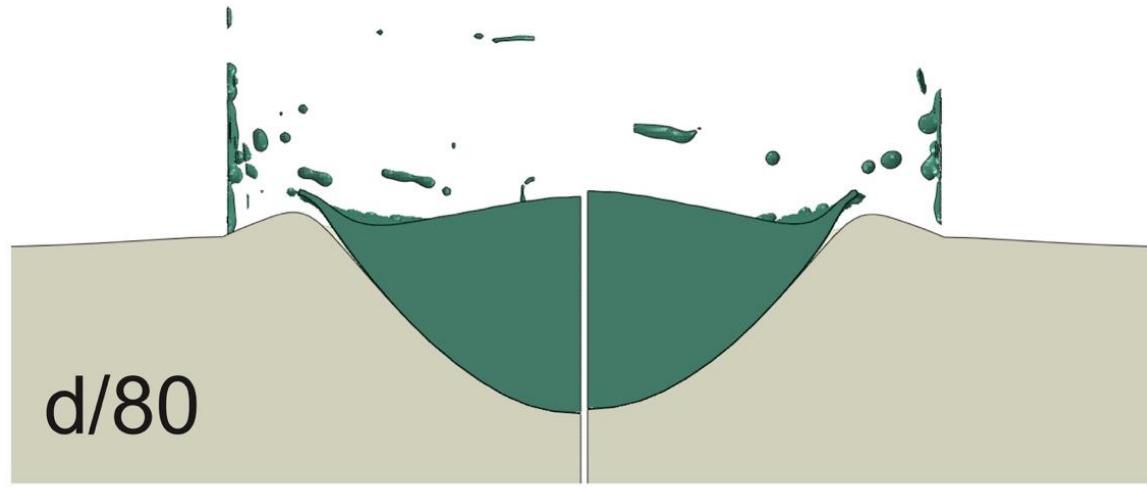
Develop a mechanistic prediction of  $V_{cr}$  for bonding

# Origin of jetting/bonding: Adiabatic Instability?

- Cu Particle/Substrate
- $V_{cr}=550$  m/s

Johnson-Cook Plasticity

$$\sigma_y = [A + B\varepsilon_p^n] \left[ 1 + C \ln \frac{\dot{\varepsilon}_p}{\dot{\varepsilon}_0} \right] \left[ 1 - \left( \frac{T - T_{ref}}{T_{melt} - T_{ref}} \right)^m \right]$$



With  
Thermal Softening

Without  
Thermal Softening

The origin of jetting?

Adiabatic Shear Instability X



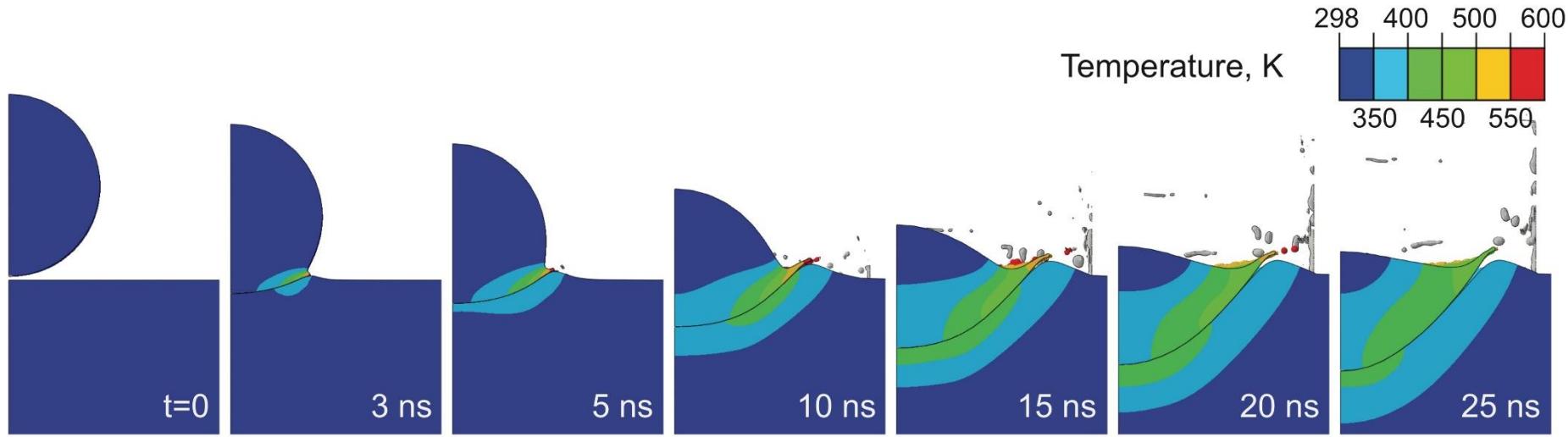
Jetting leads to Bonding.



Develop a mechanistic prediction of  $V_{cr}$  for bonding

# Localized Melting?

b

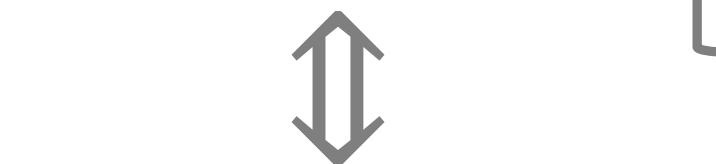


Cu,  $V_i=550$  m/s

The origin of jetting?

Adiabatic Shear Instability      X

Localized Melting      X

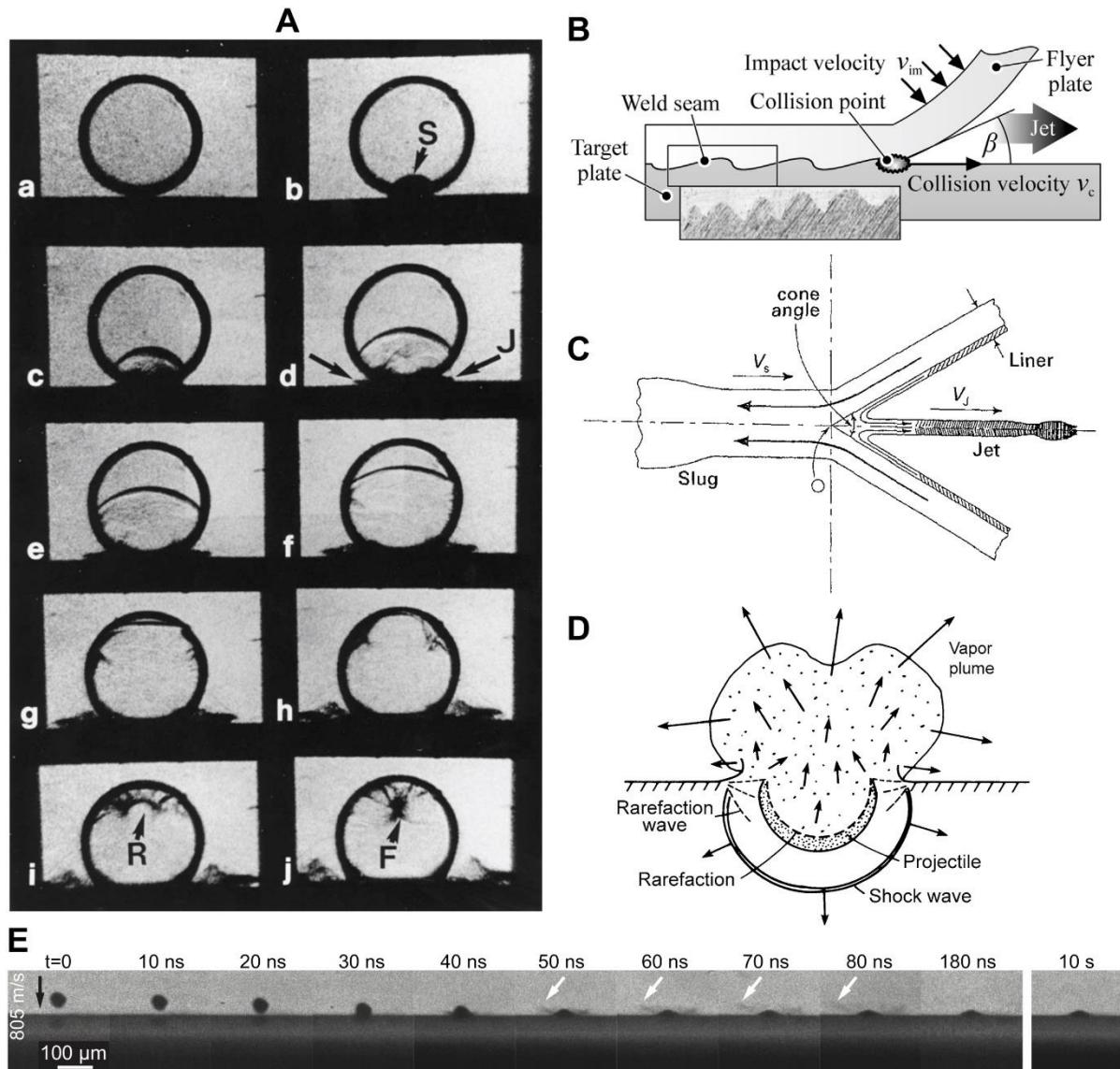


Jetting leads to Bonding.



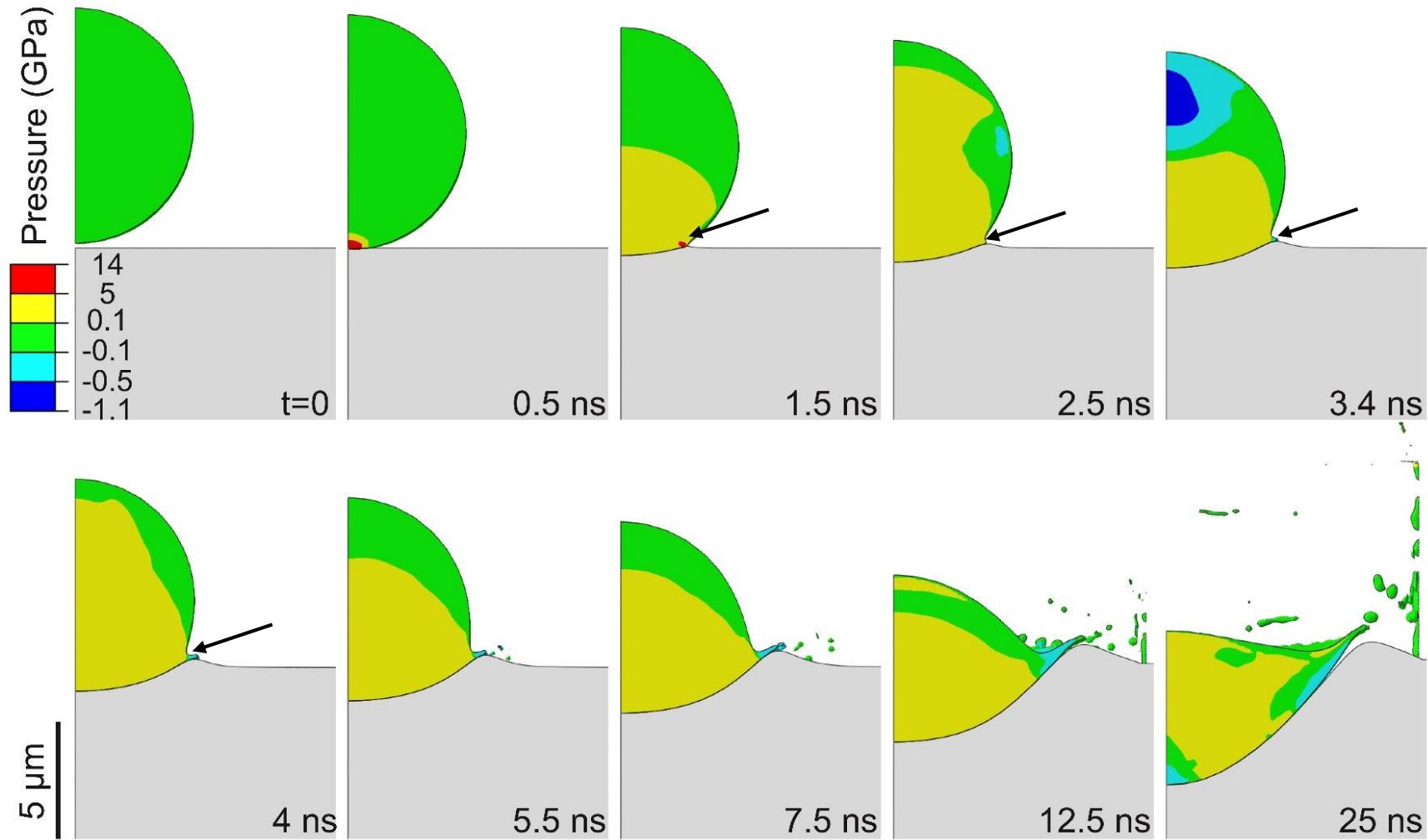
Develop a mechanistic prediction of  $V_{cr}$  for bonding

# Jetting, a hydrodynamic phenomenon

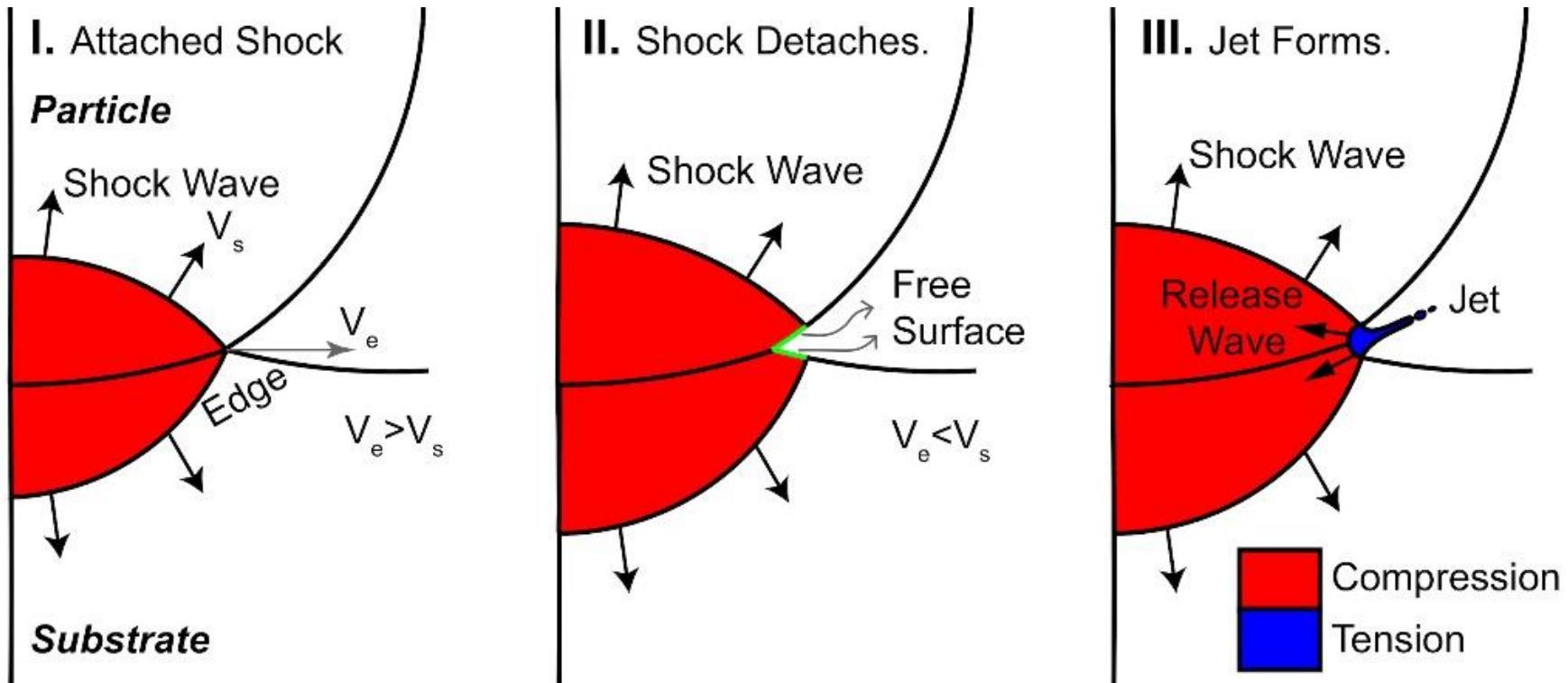


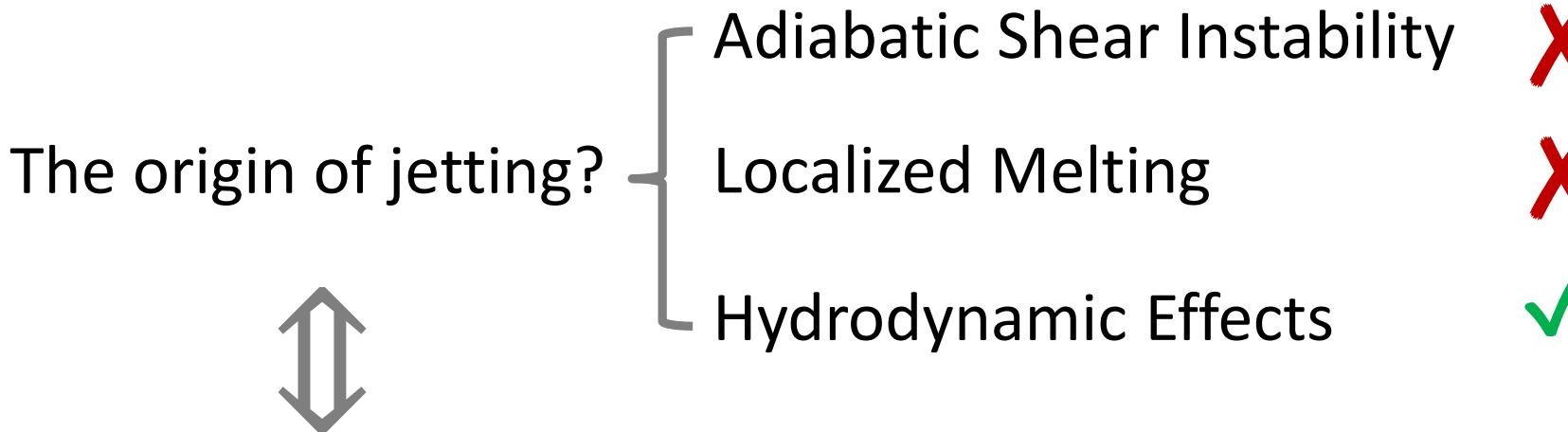
Hahn et al. J. Mater. Process. Technol. (2016); Murr et al. J. Mater. Sci. (1995); Field et al. Wear (2012); Glass et al. Springer (2012)

# Hydrodynamic Origin of Jetting



# Material ejection/fragmentation



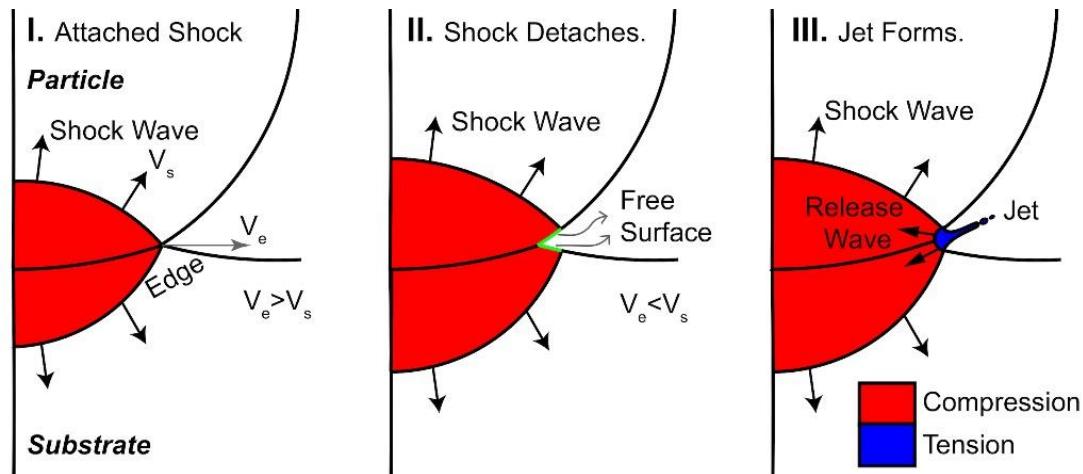


Jetting leads to Bonding.



Develop a mechanistic prediction of  $V_{cr}$  for bonding

# Material ejection/fragmentation



$$P^- = P_{spall}$$

$$P^- = kP$$

$$P_{spall} = \alpha B$$

$$k \times \left\{ \frac{1}{2} \left( \rho C_0 V_{cr} + s \frac{\rho V_{cr}^2}{2} \right) \right\} = \alpha B$$

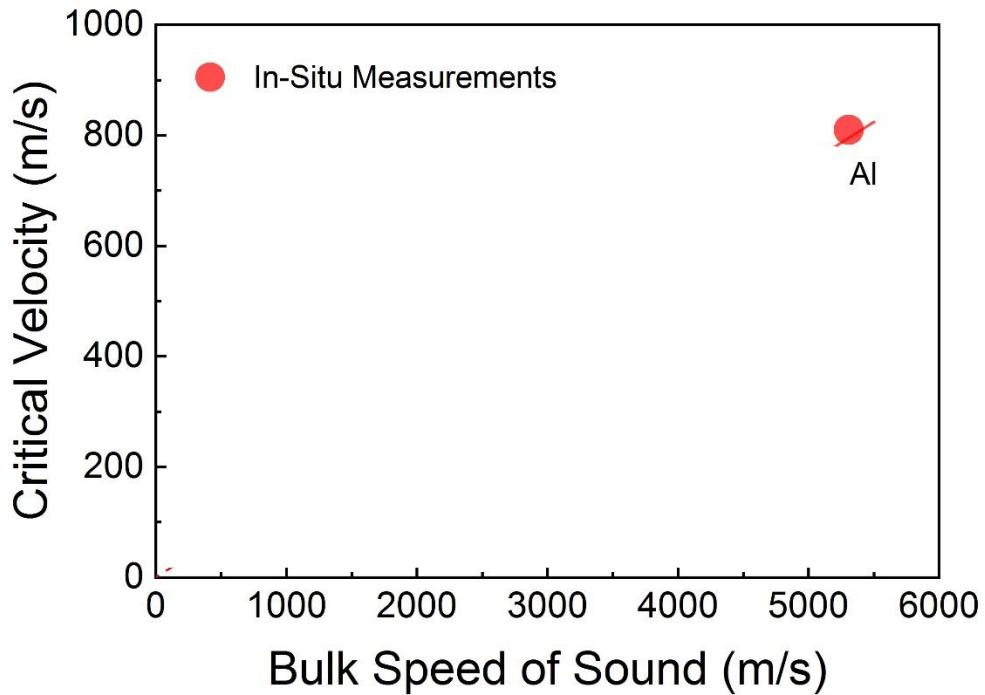
$$V_{cr} = \left( \frac{\sqrt{1 + \frac{4s\alpha}{k}} - 1}{s} \right) \times \sqrt{\frac{B}{\rho}}$$

$$V_{cr} = c \times C_0$$

# $V_{cr}$ and $C_0$

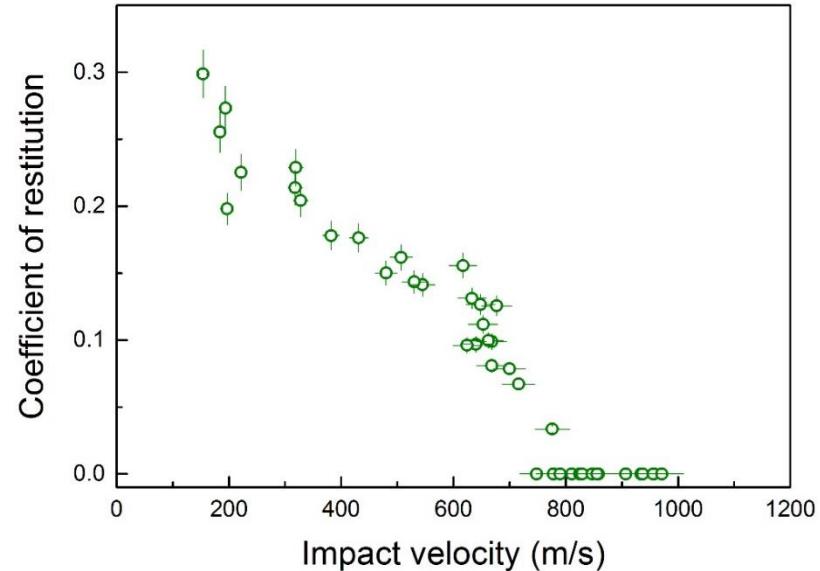
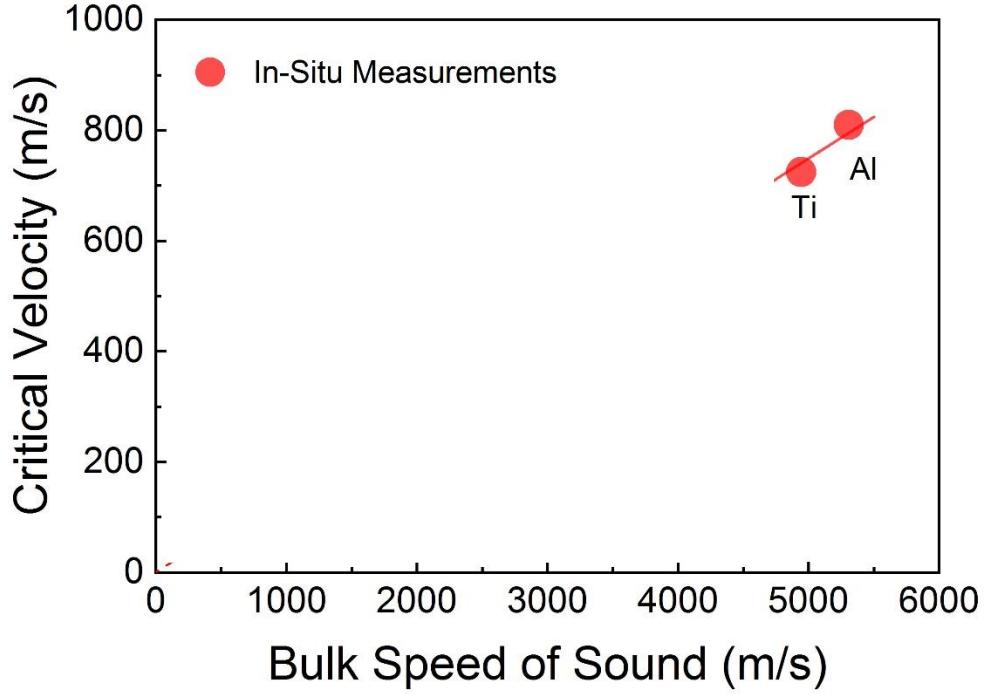
$$V_{cr} = c \times C_0$$

$$c \approx 0.15$$

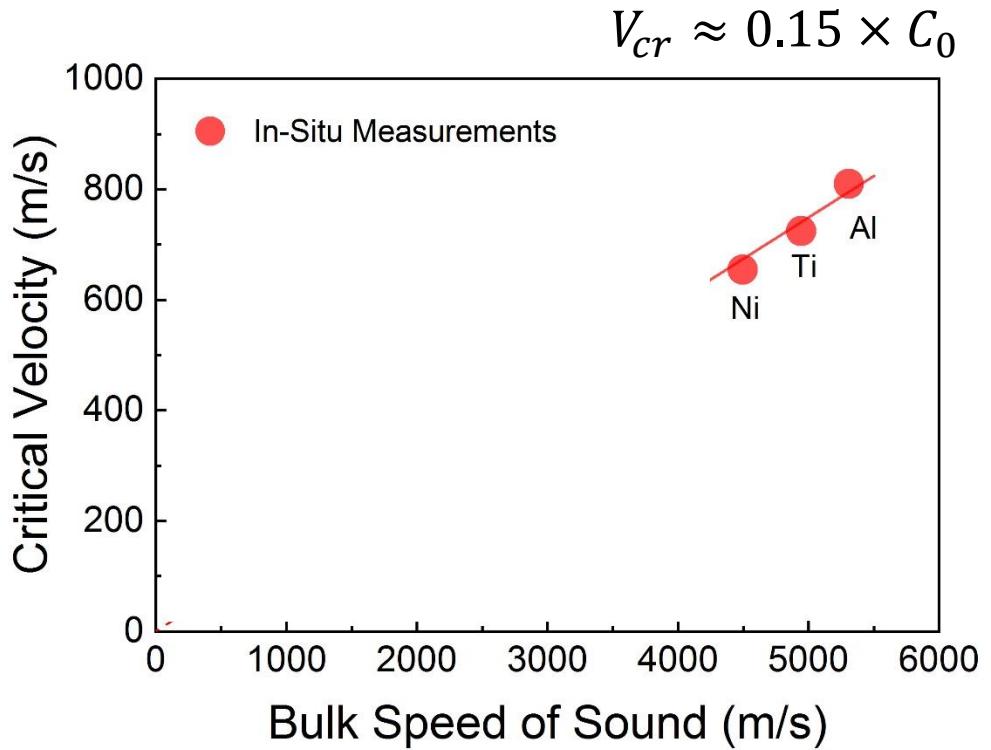
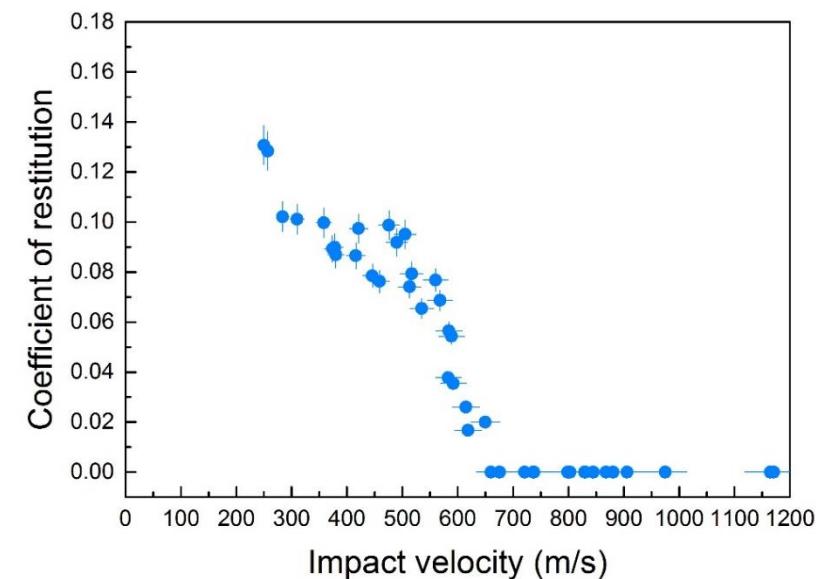


# Ti on Ti

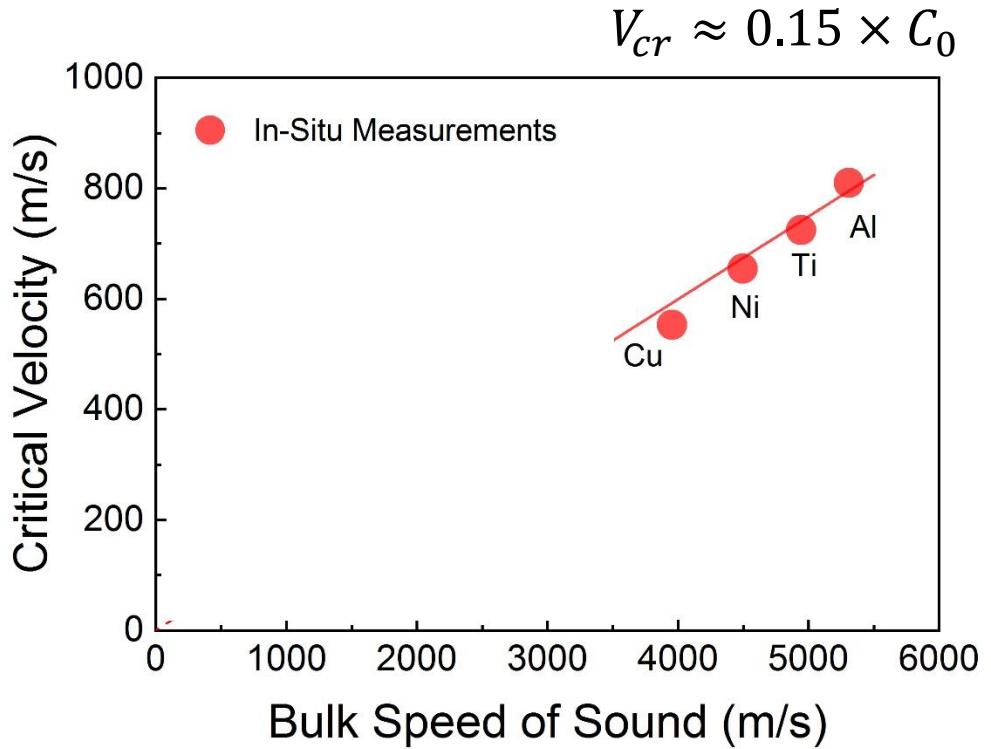
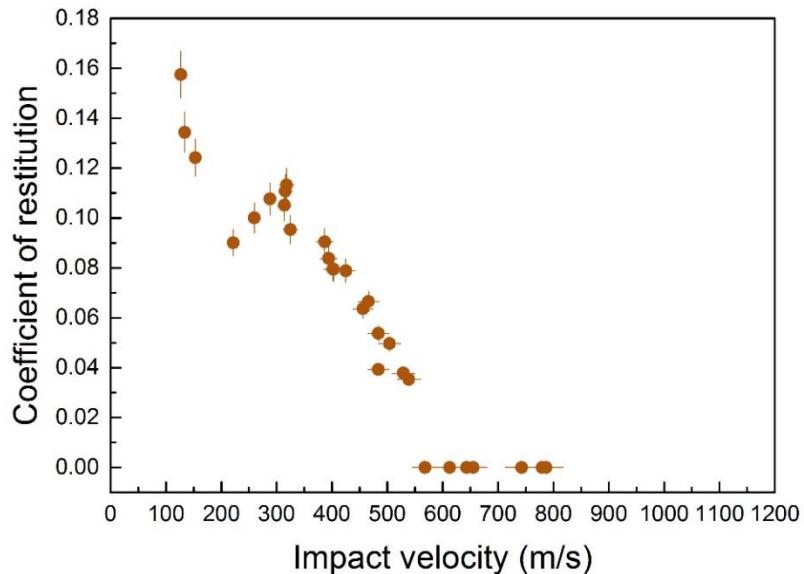
$$V_{cr} \approx 0.15 \times C_0$$



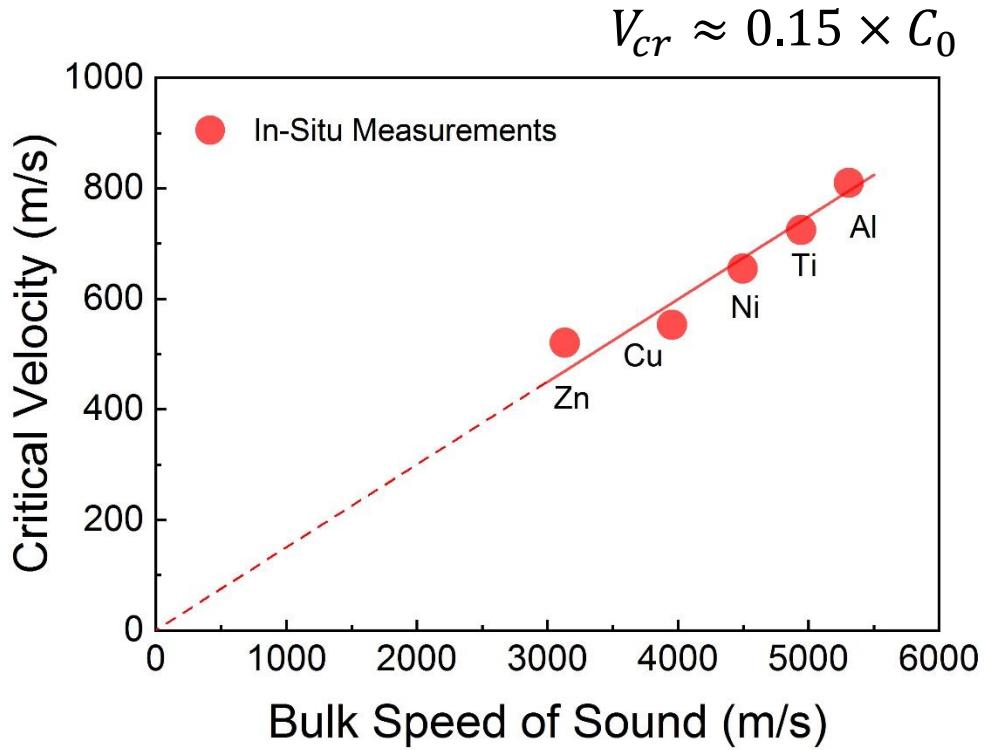
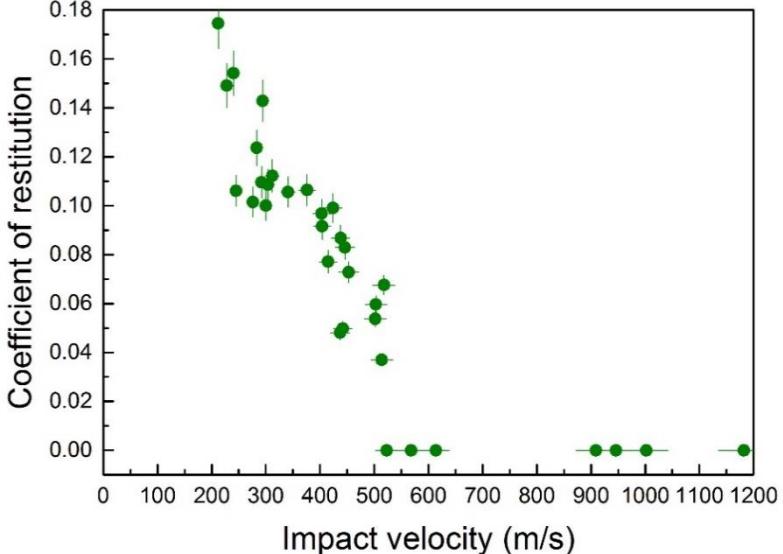
# Ni on Ni



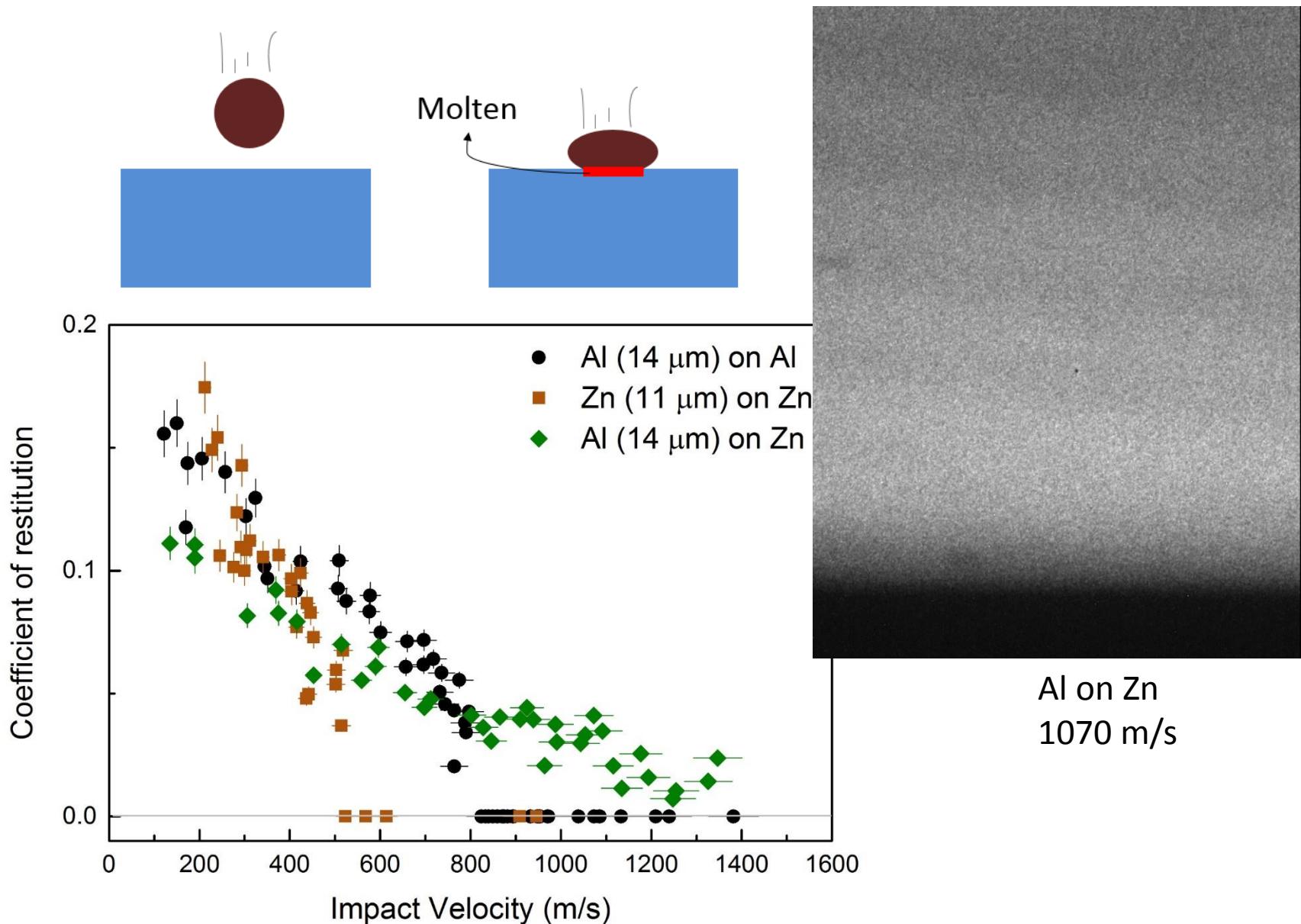
# Cu on Cu



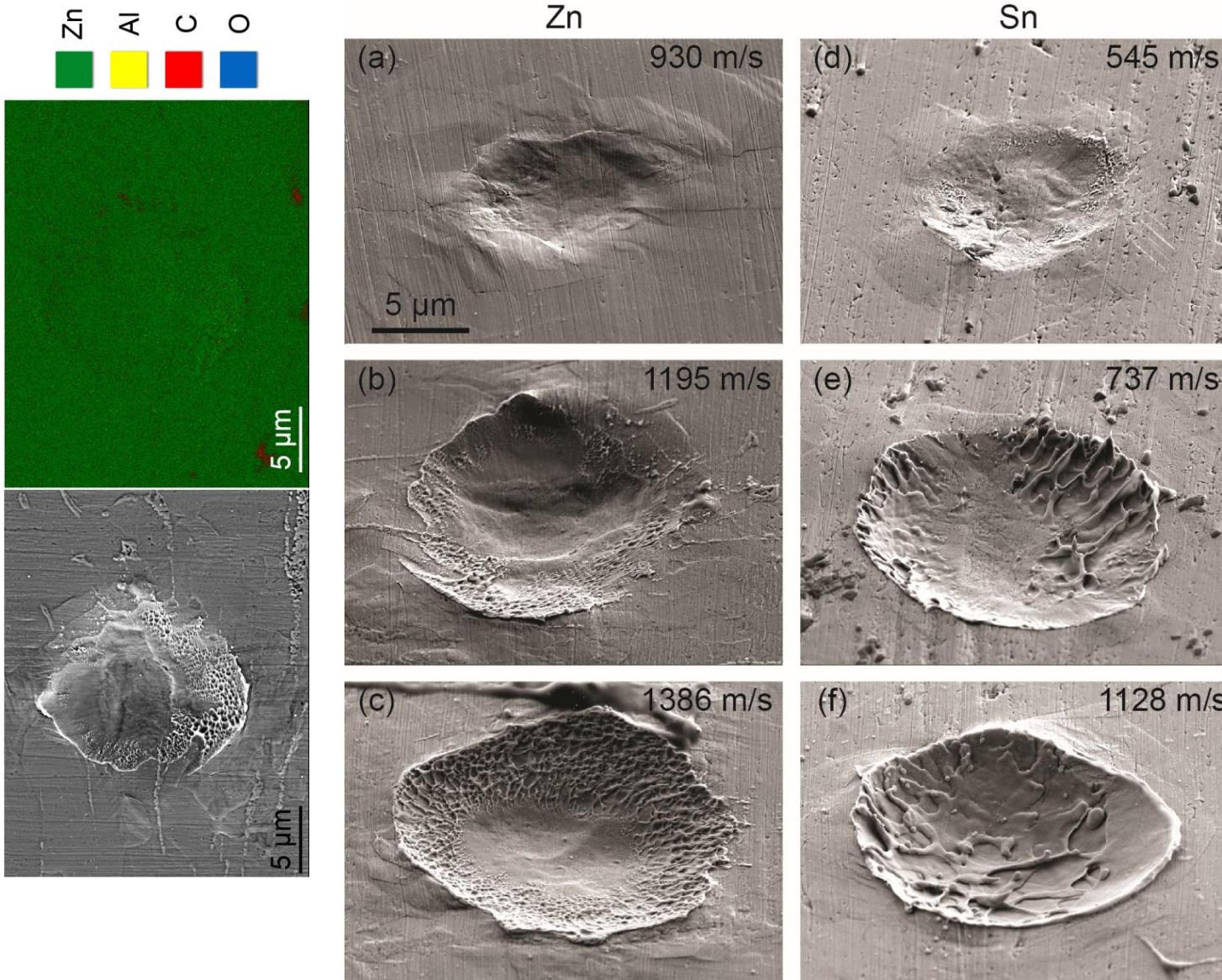
# Zn on Zn



# Melting Promotes Bonding?



# Melting emerges ...



# Time

## residence time

$$t_r = \frac{d}{V_i}$$

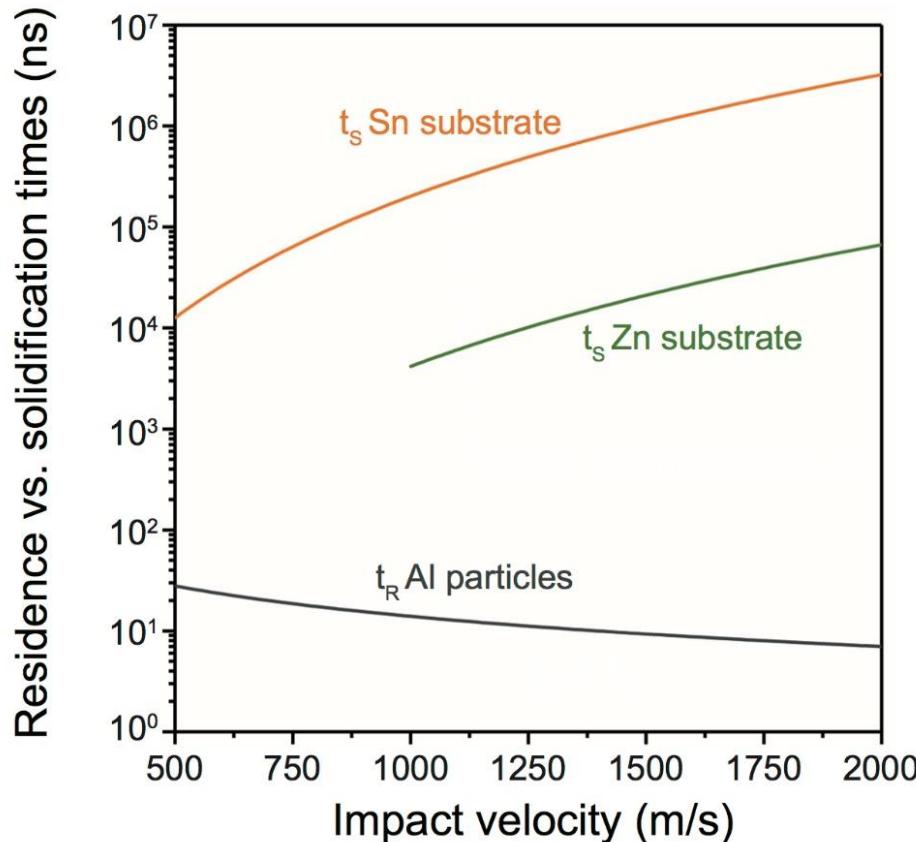
$d$ : particle size

$V_i$ : impact velocity

## solidification time

$$t_s = \left[ \frac{H_f}{(T_m - T_0)} \right]^2 \left[ \frac{\rho_s \pi}{4KC} \right] \left( \frac{v_{melt}}{A} \right)^2$$

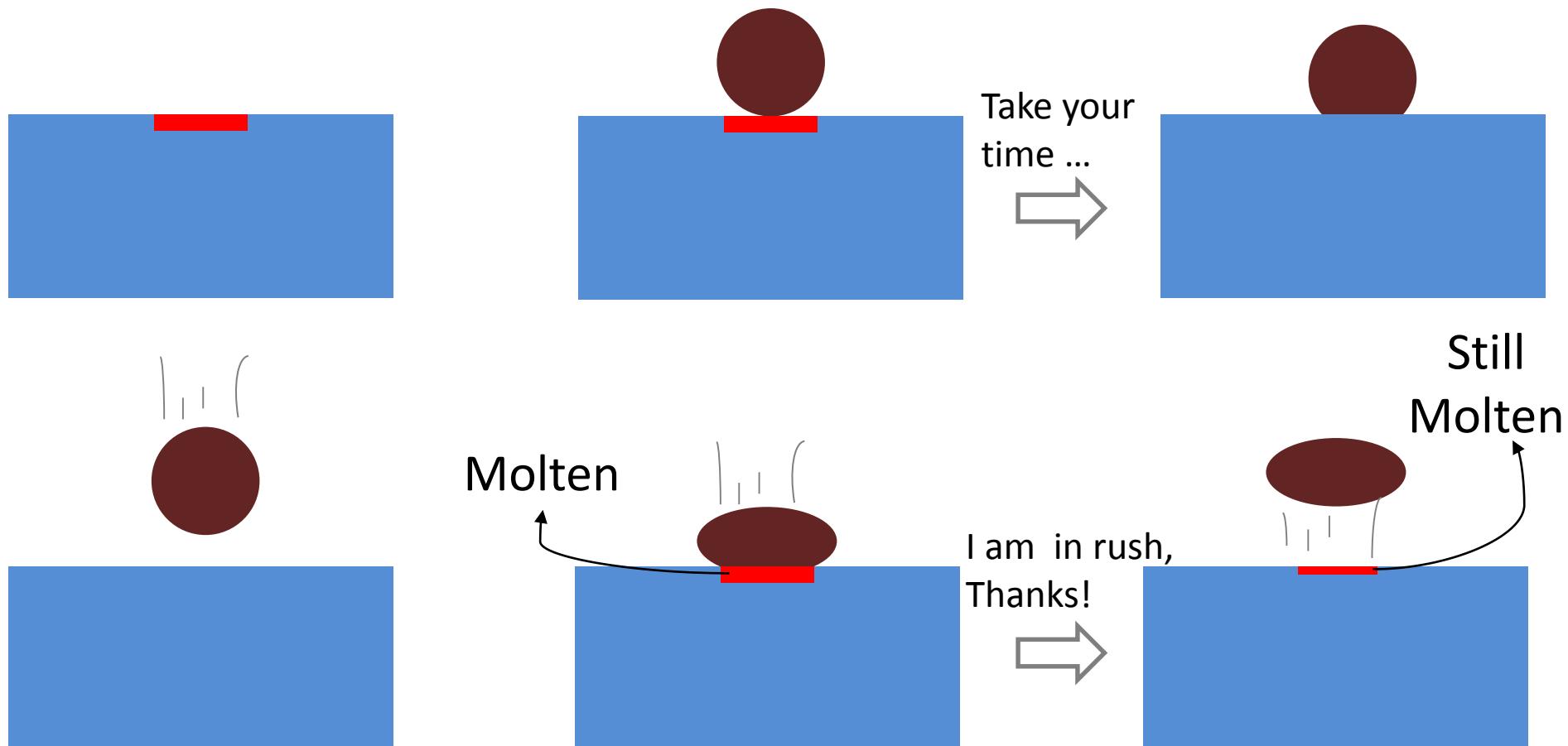
$$\frac{\rho_s v_{melt}}{m_p} = k \left( \frac{V_i^2}{E_m} \right)^{3\mu/2}$$



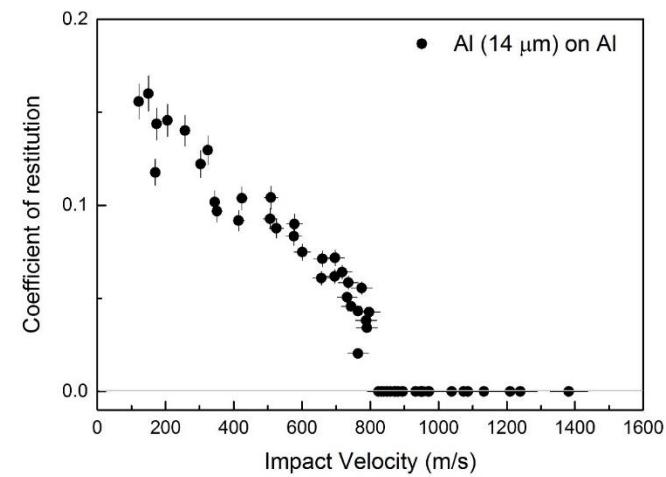
- $H_f$ : heat of fusion
- $T_m$ : melting temperature
- $T_0$ : initial temperature
- $\rho$ : density
- $K$ : thermal conductivity
- $C$ : specific heat
- $v_{melt}$ : melt volume
- $A$ : melt area
- $E_m$ : Shock energy at melting onset

# Melting and Rebound?

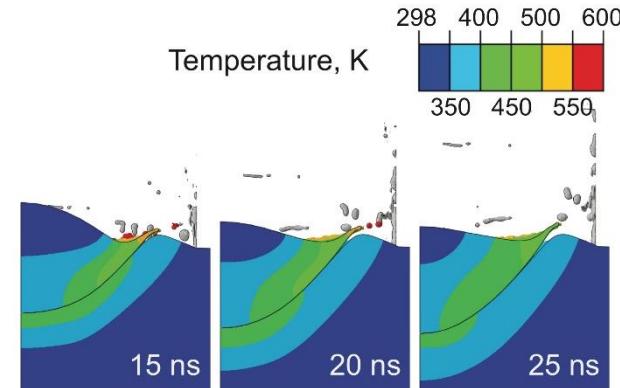
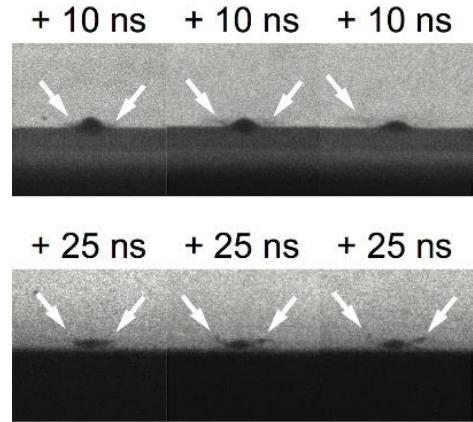
**residence time**      vs.      **solidification time**



# Summary

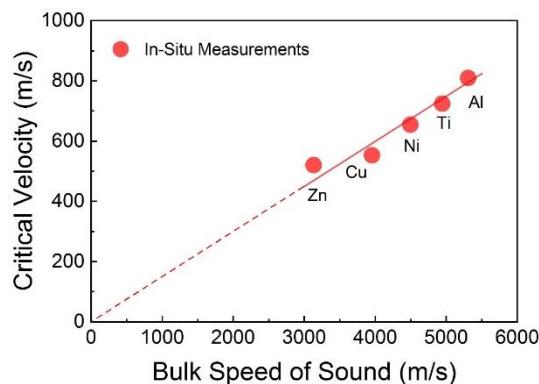
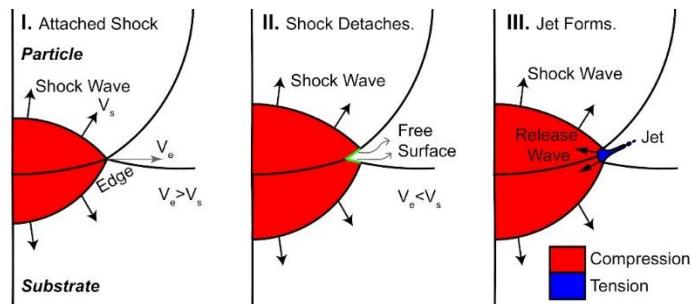


Direct measurements of  $V_{\text{cr}}$



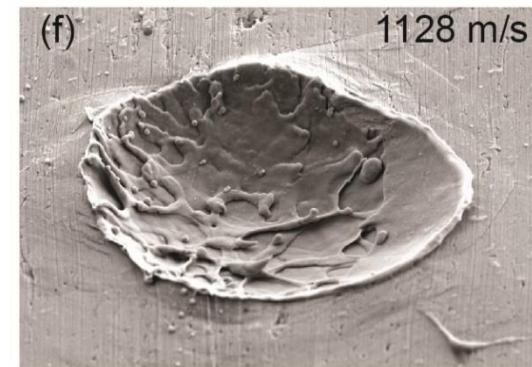
Material  
ejection/fragmentation  
upon bonding

No melting at the  
critical velocity.



Hydrodynamics origin of jetting.

$$V_{\text{cr}} = c \times C_0$$



Localized melting can  
hinder bonding.

# Acknowledgement



Hassani-Gangaraj et al. “Melting can hinder impact-induced adhesion”  
***Physical Review Letters.*** 119 (2017) 175701

Hassani-Gangaraj et al. “In-situ observations of single micro-particle impact bonding” ***Scripta Materialia.*** 145 (2018) 9.

Videos available in the supplementary materials.

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